



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Min-Lung HUANG et al. Confirmation No: 8687  
Appl. No. : 10/820,855  
Filed : April 9, 2004  
Title : Under Bump Metallization Structure Of A Semiconductor Wafer

TC/A.U. : 2813  
Examiner : D. S. Blum

Docket No.: : HUAN3262/REF  
Customer No: : 23364

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action of April 11, 2006, in connection with the above-identified application. The period for response to the Official Action has been extended to expire on August 11, 2006 by the filing herewith of a Petition for a One Month Extension of Time and payment of the required fees.

Please amend the application as follows:

Amendments to the specification begin on page 2 of this paper.

Amendments to the claims are reflected in the listing of claims which begins on page 5 of this paper.

Remarks begin on page 8 of this paper.